

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|-----------------|-------------------|--|------------|--------------|-------------------------|----------------|
| Die | Metal oxide | Lead Dioxide (PbO2) | 1309-60-0 | 0 | 0.97 | 0.04 |
| | Doped silicon | Silicon (Si) | 7440-21-3 | 0.18 | 99.03 | 3.66 |
| Subtotal | | | | 0.18 | 100 | 3.7 |
| Solder Wire | Tin alloy | Tin (Sn) | 7440-31-5 | 0.01 | 10.0 | 0.24 |
| | Silver alloy | Silver (Ag) | 7440-22-4 | 0 | 2.0 | 0.05 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 0.1 | 88.0 | 2.12 |
| Subtotal | | | | 0.11 | 100 | 2.41 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.4 | 100.0 | 8.16 |
| | | | | | | |
| Lead Frame | Iron-nickel alloy | Phosphorous (P) | 7723-14-0 | 0.02 | 0.03 | 0.41 |
| | Iron-nickel alloy | Nickel (Ni) - cas no. 7440-02-0 | 7440-02-0 | 0.73 | 1.08 | 14.86 |
| | Iron-nickel alloy | Copper (Cu) | 7440-50-8 | 66.9 | 98.79 | 1359.35 |
| Subtotal | | | | 67.65 | 99.9 | 1374.62 |
| Post-plating | Pure metal | Tin (Sn) | 7440-31-5 | 1.02 | 100.0 | 20.68 |
| | | | | | | |
| Mould Compound | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 1.38 | 4.5 | 27.95 |
| | Polymer | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3 | 3.06 | 10.0 | 62.1 |
| | Filler | Silica fused | 60676-86-0 | 22.92 | 75.0 | 465.75 |
| | Metal hydroxide | Metal hydroxide | | 3.06 | 10.0 | 62.1 |
| | Carbon Black | Carbon black | 1333-86-4 | 0.15 | 0.5 | 3.1 |
| Subtotal | | | | 30.57 | 100 | 621 |
| Total | | | | 99.93 | 100 | 2030.57 |

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